



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



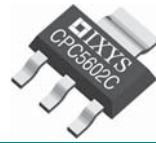
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| Parameter | Rating | Units |
|------------------------------------|--------|----------|
| Drain-to-Source Voltage - V_{DS} | 350 | V |
| Max On-Resistance - $R_{DS(on)}$ | 14 | Ω |
| Max Power | 2.5 | W |

Features

- 350V Drain-to-Source Voltage
- Depletion Mode Device Offers Low $R_{DS(on)}$ at Cold Temperatures
- Low On-resistance: 8Ω (Typical) @ 25°C
- Low $V_{GS(off)}$ Voltage: -2.0V to -3.6V
- High Input Impedance
- Low Input and Output Leakage
- Small Package Size SOT-223
- PC Card (PCMCIA) Compatible
- PCB Space and Cost Savings

Applications

- Support Component for LITELINK™ Data Access Arrangement (DAA)
- Telecommunications
- Normally On Switches
- Ignition Modules
- Converters
- Security
- Power Supplies

Description

The CPC5602 is an N-channel depletion mode Field Effect Transistor (FET) that utilizes IXYS Integrated Circuits Division's proprietary third generation vertical DMOS process. The third generation process realizes world class, high voltage MOSFET performance in an economical silicon gate process. The vertical DMOS process yields a highly reliable device, particularly in difficult application environments such as telecommunications, security, and power supplies.

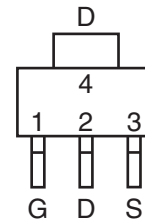
One of the primary applications for the CPC5602 is as a linear regulator/hook switch for the LITELINK family of Data Access Arrangements (DAA) Devices CPC5620A, CPC5621A, and CPC5622A.

The CPC5602 has a typical on-resistance of 8Ω , a drain-to-source voltage of 350V, and is available in an SOT-223 package. As with all MOS devices, the FET structure prevents thermal runaway and thermal-induced secondary breakdown.

Ordering Information

| Part # | Description |
|------------|--|
| CPC5602CTR | N-Channel Depletion Mode FET, SOT-223 Pkg. Tape and Reel (1000/Reel) |

Package Pinout



| Pin Number | Name |
|------------|--------|
| 1 | GATE |
| 2 | DRAIN |
| 3 | SOURCE |
| 4 | DRAIN |



Absolute Maximum Ratings @ 25°C

| Parameter | Symbol | Ratings | Units |
|---------------------------|----------|-------------|-------|
| Drain-to-Source Voltage | V_{DS} | 350 | V |
| Gate-to-Source Voltage | V_{GS} | ±20 | V |
| Total Package Dissipation | P | 2.5 | W |
| Operational Temperature | T_A | -40 to +85 | °C |
| Storage Temperature | T_A | -40 to +125 | °C |

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

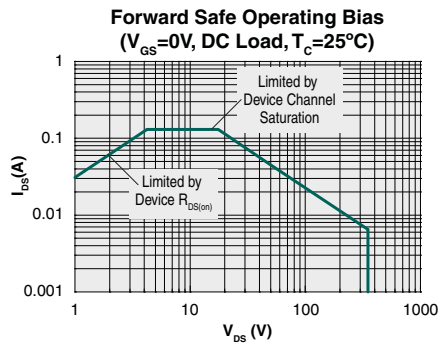
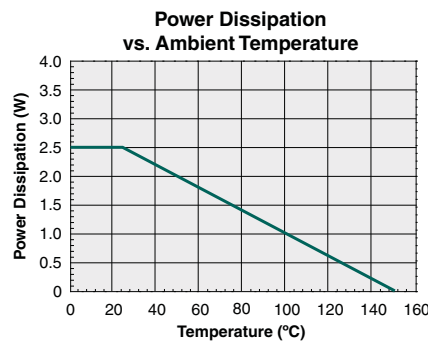
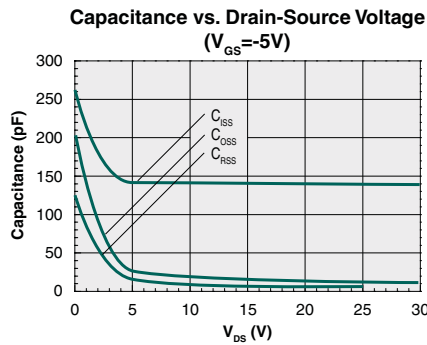
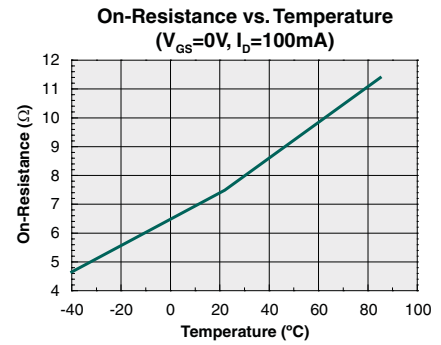
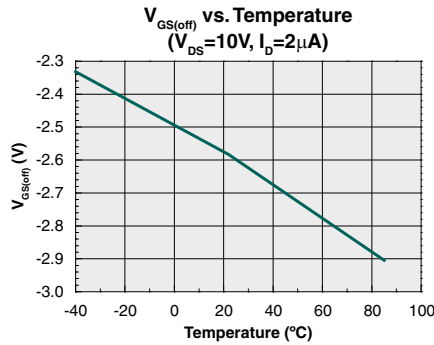
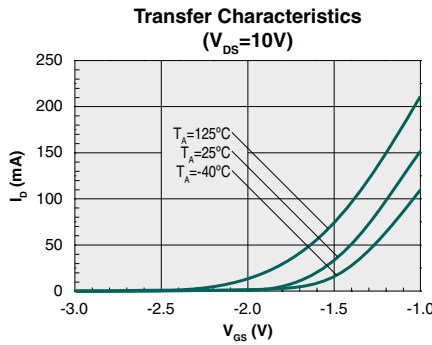
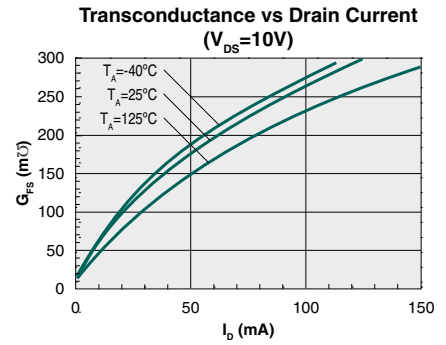
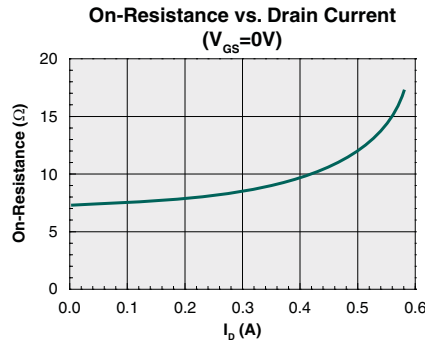
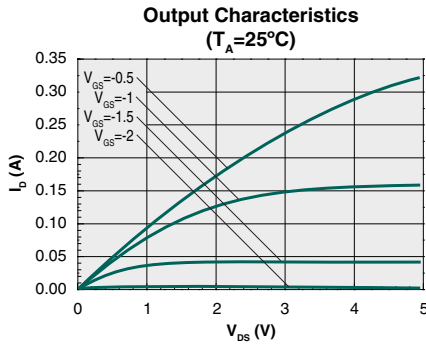
Electrical Characteristics @25°C (Unless Otherwise Specified)

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
|---------------------------------|---------------|---|-----|-------|------|-------|
| Gate-to-Source Off Voltage | $V_{GS(off)}$ | $I_D = 2\mu A, V_{DS} = 10V, V_{DS} = 100V$ | -2 | -2.62 | -3.6 | V |
| Drain-to-Source Leakage Current | $I_{DS(off)}$ | $V_{GS} = -5V, V_{DS} = 190V$ | - | - | 20 | nA |
| | | $V_{GS} = -5V, V_{DS} = 350V$ | - | - | 1 | μA |
| Drain Current | I_D | $V_{GS} = -2.7V, V_{DS} = 5V, V_{DS} = 50V$ | - | - | 5 | mA |
| | | $V_{GS} = -0.57V, V_{DS} = 5V$ | 130 | - | - | mA |
| On-Resistance | $R_{DS(on)}$ | $V_{GS} = -0.35V, I_{DS} = 50mA$ | - | 8 | 14 | Ω |
| Gate Leakage Current | I_{GSS} | $V_{GS} = 10V, V_{GS} = -10V$ | - | - | 0.1 | μA |
| Gate Capacitance | C_{ISS} | $V_{DS} = V_{GS} = 0V$ | - | - | 300 | pF |

Thermal Characteristics

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
|--------------------|-----------------|------------|-----|-----|-----|-------|
| Thermal Resistance | $R_{\theta JC}$ | - | - | - | 14 | °C/W |

PERFORMANCE DATA *



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

| Device | Moisture Sensitivity Level (MSL) Rating |
|----------|---|
| CPC5602C | MSL 1 |

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

| Device | Maximum Temperature x Time |
|----------|----------------------------|
| CPC5602C | 260°C for 30 seconds |

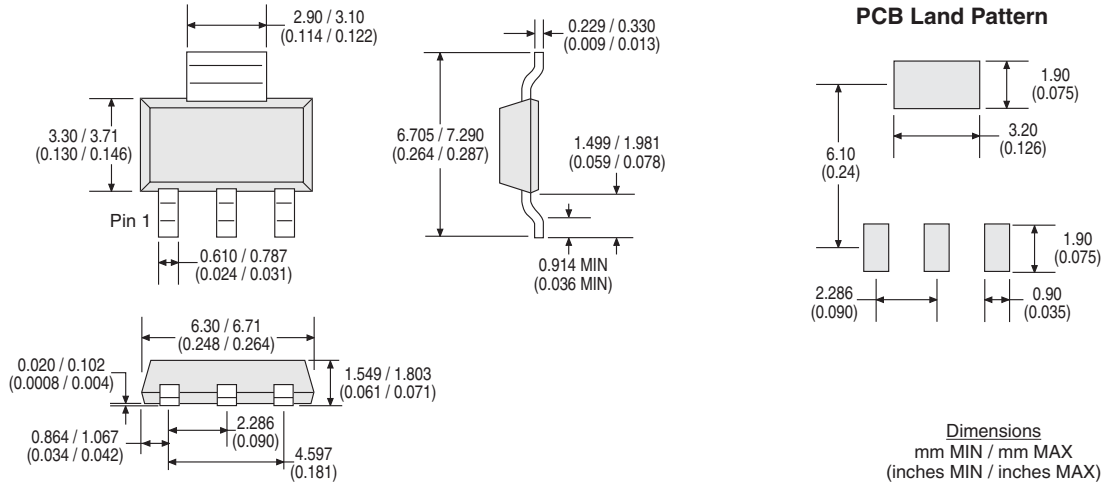
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable, and the use of a short drying bake may be necessary. Chlorine-based or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

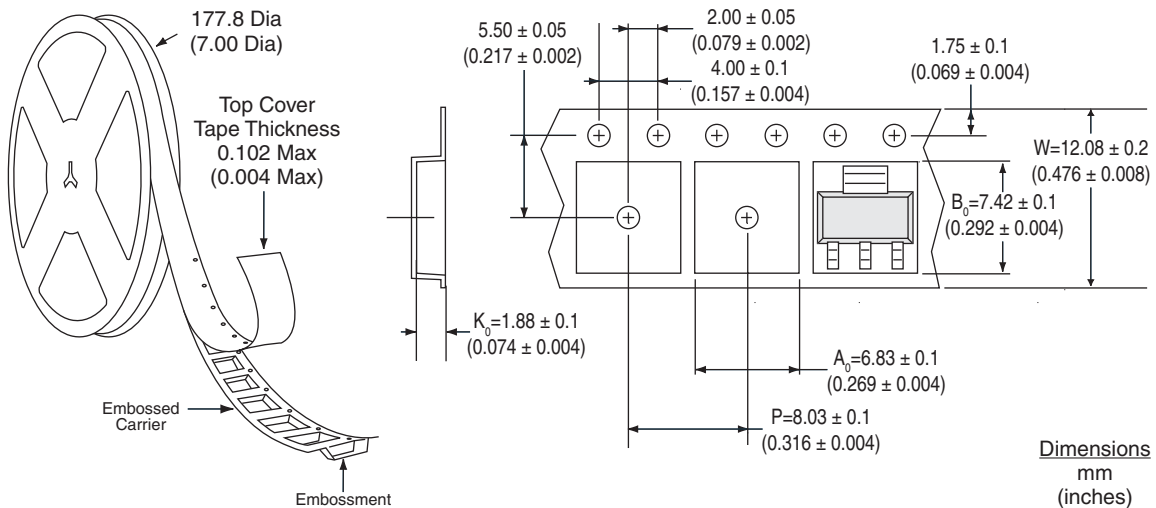


MECHANICAL DIMENSIONS

CPC5602C



CPC5602CTR Tape & Reel



For additional information please visit our website at: www.ixysic.com

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